

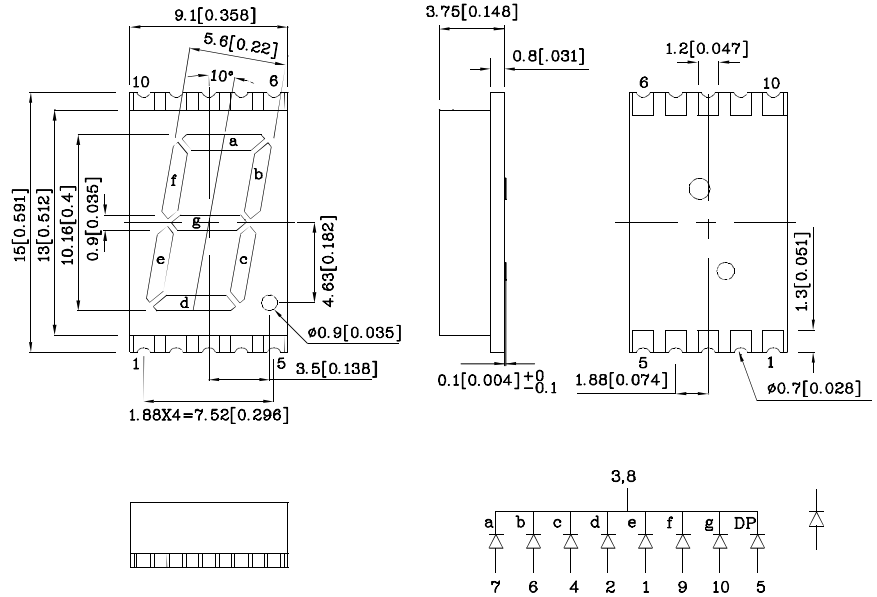
Features

- 0.4 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 400pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

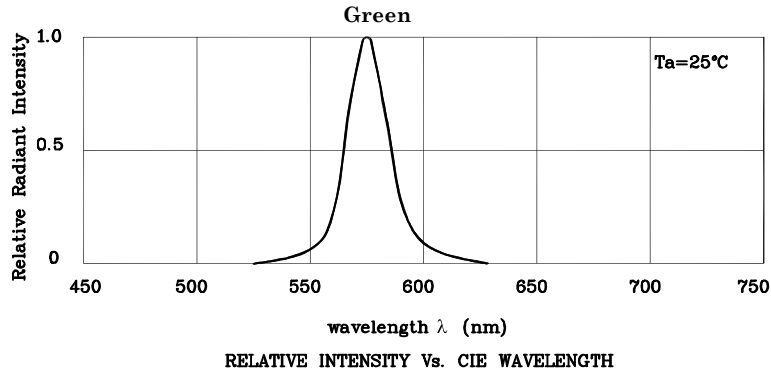
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		Green (AlGaInP)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	150	mA
Power Dissipation	P_D	75	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

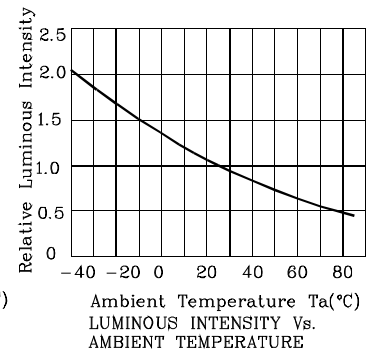
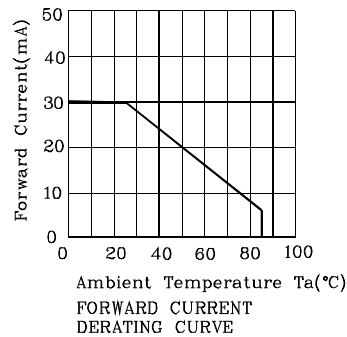
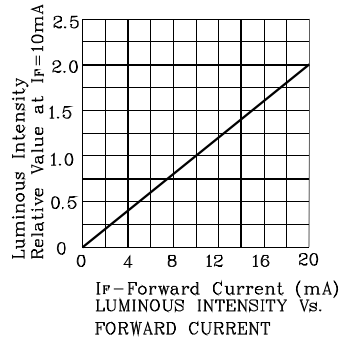
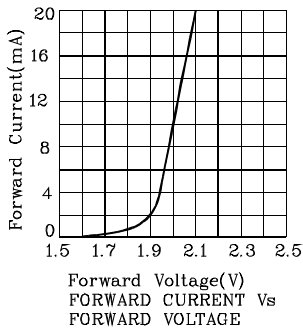
Operating Characteristics ($T_A=25^\circ\text{C}$)		Green (AlGaInP)	Unit
Forward Voltage (Typ.) ($I_F=10\text{mA}$)	V_F	2	V
Forward Voltage (Max.) ($I_F=10\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission CIE127-2007* (Typ.) ($I_F=10\text{mA}$)	λ_P	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ($I_F=10\text{mA}$)	λ_D	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=10\text{mA}$)	$\Delta\lambda$	20	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ($I_F=10\text{mA}$) ucd		Wavelength CIE127-2007* nm λ_P	Description
			min.	typ.		
XZFGV10C	Green	AlGaInP	5600 2200*	10990 4090*	574*	Common Cathode, Rt.Hand Decimal.

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Green



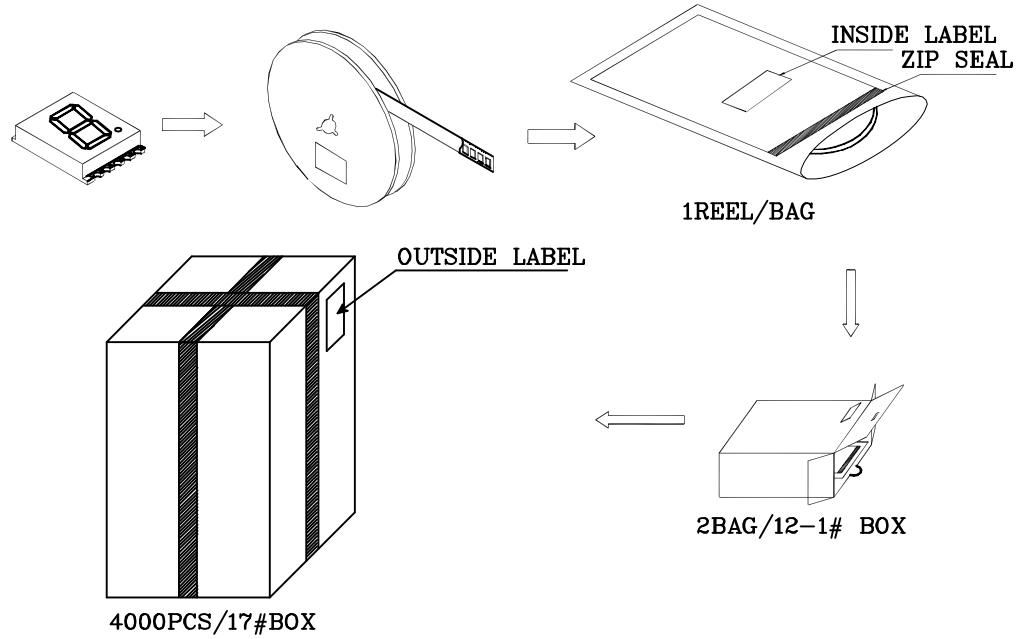
LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

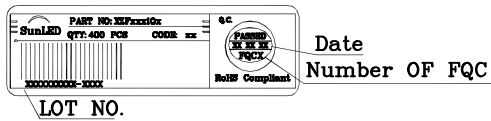


1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C-260°C
3. Do not put stress to the epoxy resin during high temperatures conditions

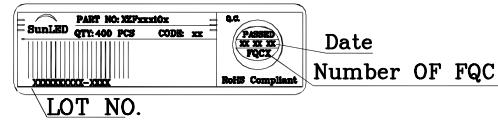
PACKING & LABEL SPECIFICATIONS



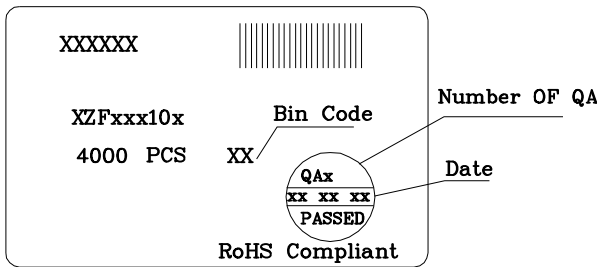
Inside Label On tape



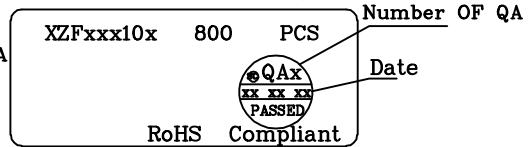
Outside Label On Bag



Outside Label On 17#Box



Outside Label On 12-1#Box



TERMS OF USE

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>